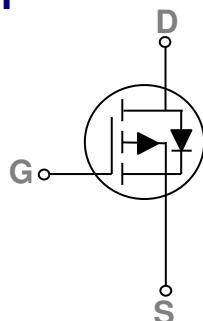
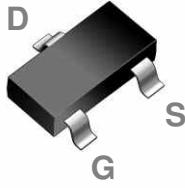


### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOT323 Pin Configuration



BVDSS	RDS(ON)	ID
-20V	90mΩ	-1.5A

### Features

- -20V, -1.5A, RDS(ON) = 90mΩ@VGS = -4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications

### Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

### Absolute Maximum Ratings T<sub>c</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-20	V
V <sub>GS</sub>	Gate-Source Voltage	±10	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25°C)	-1.5	A
	Drain Current – Continuous (T <sub>c</sub> =100°C)	-0.95	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-6	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	312	mW
	Power Dissipation – Derate above 25°C	2.5	mW/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	400	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-20	---	---	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =-1mA	---	-0.01	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	-10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DSON</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-1A	---	75	90	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-1A	---	100	130	
		V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-1A	---	130	170	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-0.3	-0.6	-1.0	V
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	3	---	mV/°C
g <sub>f</sub> s	Forward Transconductance	V <sub>DS</sub> =-10V, I <sub>S</sub> =-1A	---	2.2	---	S

**Dynamic and switching Characteristics**

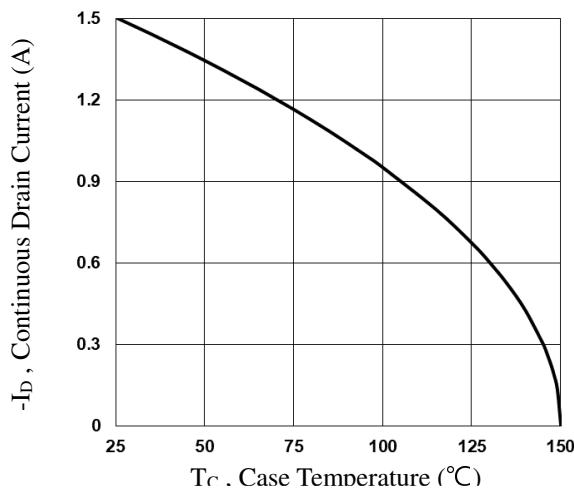
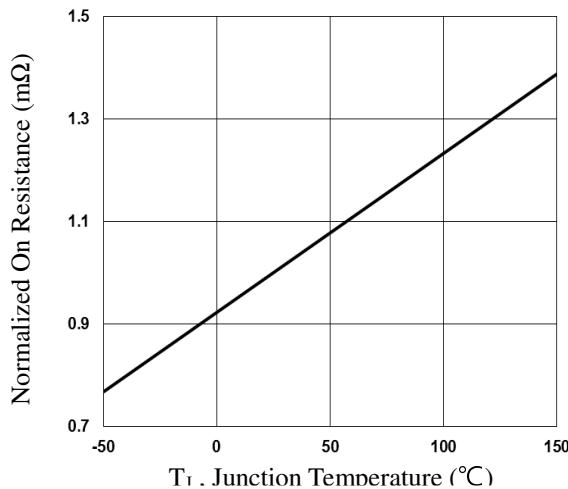
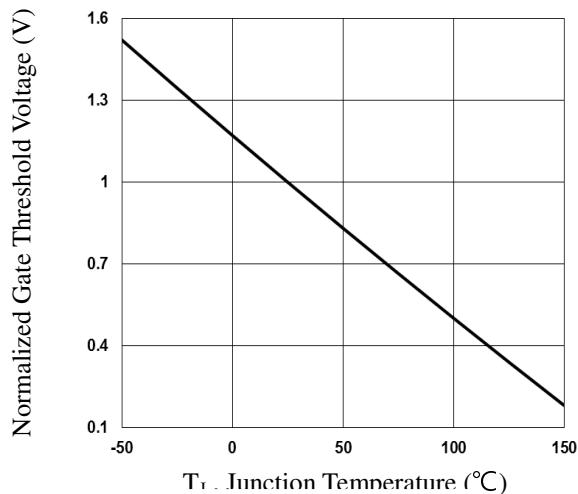
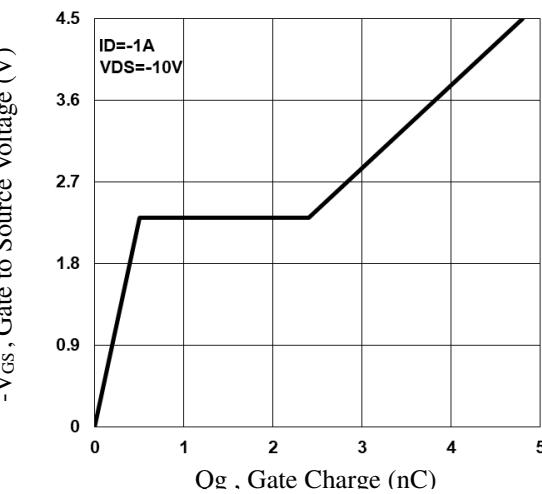
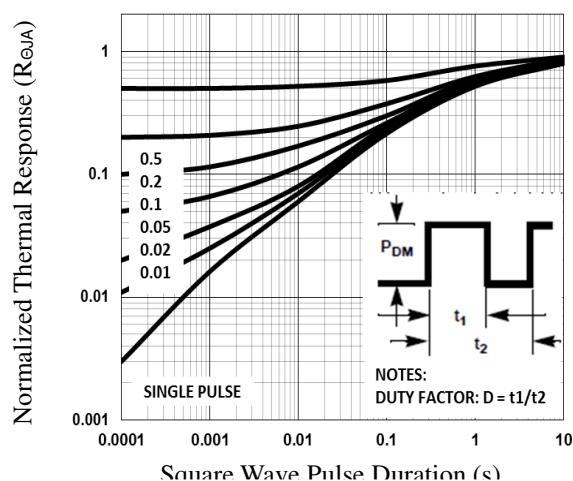
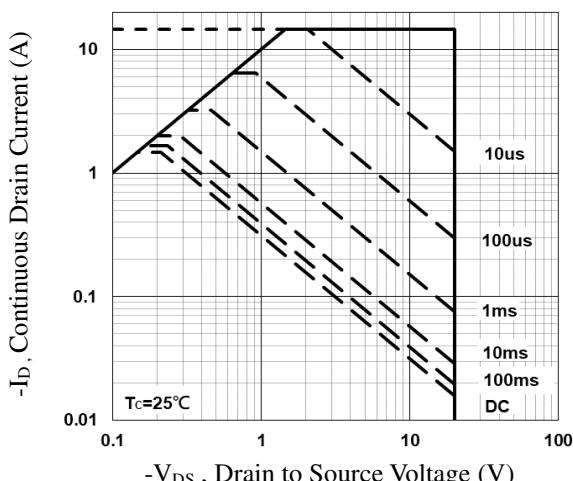
Q <sub>g</sub>	Total Gate Charge <sup>2,3</sup>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-1A	---	4.8	8	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2,3</sup>		---	0.5	1	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2,3</sup>		---	1.9	4	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2,3</sup>	V <sub>DD</sub> =-10V, V <sub>GS</sub> =-4.5V, R <sub>G</sub> =25Ω I <sub>D</sub> =-1A	---	3.5	7	ns
T <sub>r</sub>	Rise Time <sup>2,3</sup>		---	12.6	24	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2,3</sup>		---	32.6	62	
T <sub>f</sub>	Fall Time <sup>2,3</sup>		---	8.4	16	
C <sub>iss</sub>	Input Capacitance		---	350	510	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, F=1MHz	---	65	95	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	50	75	

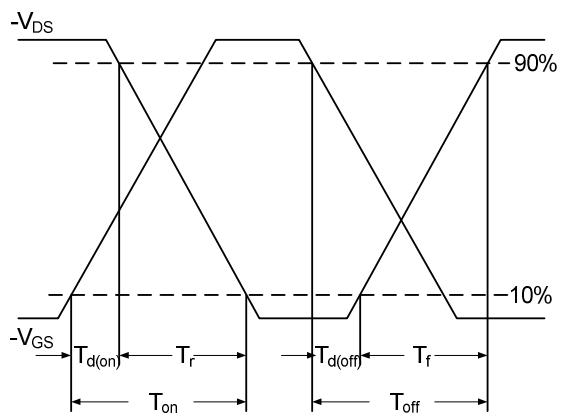
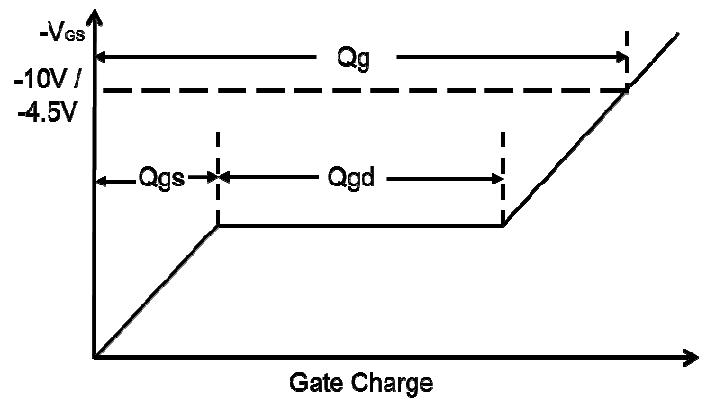
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-1.5	A
I <sub>SM</sub>	Pulsed Source Current		---	---	-3	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1	V

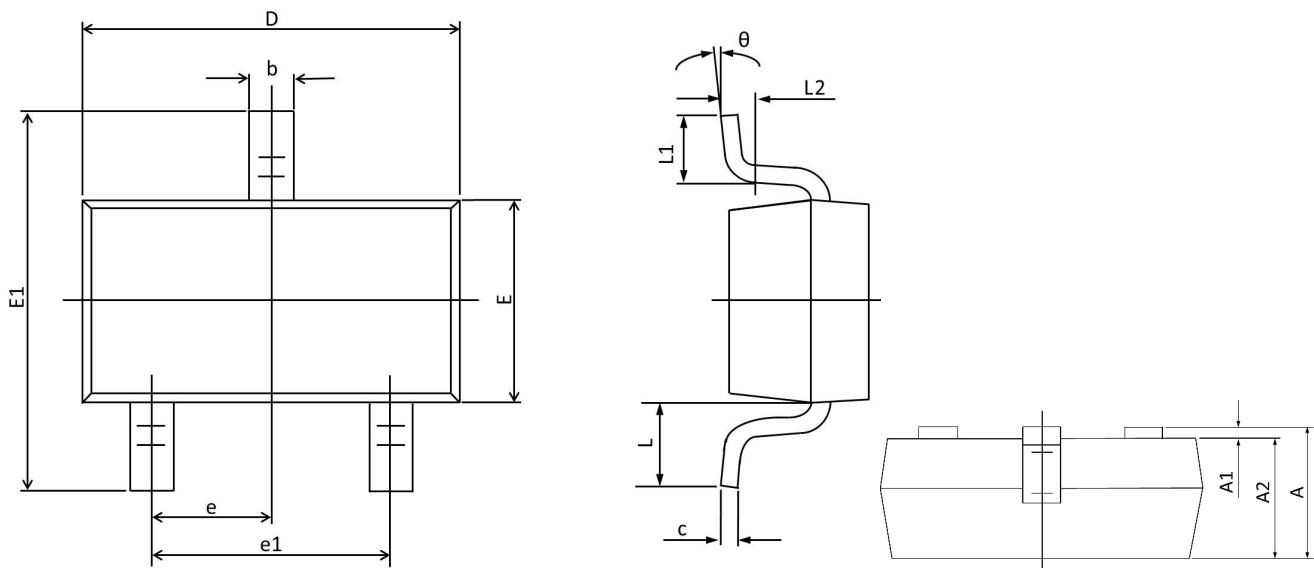
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**

**Fig.2 Normalized RDSON vs. T<sub>J</sub>**

**Fig.3 Normalized V<sub>th</sub> vs. T<sub>J</sub>**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**


**Fig.7** Switching Time Waveform

**Fig.8** Gate Charge Waveform

## SOT323 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
A1	0.100	0.000	0.004	0.000
A2	1.000	0.800	0.039	0.031
b	0.400	0.200	0.016	0.008
c	0.250	0.080	0.010	0.003
D	2.200	1.800	0.087	0.071
E	1.350	1.150	0.053	0.045
E1	2.450	1.800	0.096	0.071
e	0.65BSC		0.026BSC	
e1	1.400	1.200	0.055	0.047
L	0.525REF.		0.021REF.	
L1	0.460	0.150	0.018	0.006
L2	0.200	0.000	0.008	0.000
θ	8°	0°	8°	0°